5-Line Transient Voltage Suppressor Array

This 5-line voltage transient suppressor array is designed for application requiring transient voltage protection capability. It is intended for use in over-transient voltage and ESD sensitive equipment such as computers, printers, automotive electronics, networking communication and other applications. This device features a monolithic common anode design which protects five independent lines in a single TSOP-6 package.

- Protects up to 5 Lines in a Single TSOP-6 Package
- Peak Power Dissipation 350 W (8 × 20 μs Waveform)
- ESD Rating of Class 3B (Exceeding 8.0 kV) per Human Body Model and Class C (Exceeding 400 V) per Machine Model
- Compliance with IEC 61000-4-2 (ESD) 15 kV (Air), 8.0 kV (Contact)
- Flammability Rating of UL 94 V-0
- These are Pb-Free Devices

Applications

- Hand-Held Portable Applications
- Networking and Telecom
- Automotive Electronics
- Serial and Parallel Ports
- Notebooks, Desktops, Servers

MAXIMUM RATINGS (T_J = 25°C unless otherwise specified)

Symbol	Rating	Value	Unit
P _{PK} 1	Peak Power Dissipation 8 \times 20 μs Double Exponential Waveform (Note 1)	350	W
T_J	Operating Junction Temperature Range	-40 to 150	°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T_L	Lead Solder Temperature (10 s)	260	°C
ESD	Human Body Model (HBM) Machine Model (MM) IEC 61000-4-2 Air (ESD) IEC 61000-4-2 Contact (ESD)	>8000 >400 >15000 >8000	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1

1. Non-repetitive current pulse per Figure 3.



ON Semiconductor®

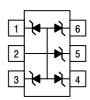
http://onsemi.com

TSOP-6 FIVE TRANSIENT VOLTAGE SUPPRESSOR 350 W PEAK POWER

PIN ASSIGNMENT



TSOP-6 **CASE 318G**



- PIN 1. CATHODE
 - 2. ANODE
 - 3. CATHODE
 - 4. CATHODE
 - 5. CATHODE
 - 6. CATHODE

MARKING DIAGRAM



- x = SMS05C:J
 - = SMS12C:K
 - = SMS15C:L
 - = SMS24C:M
- M = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
SMS05CT1G		
SMS12CT1G	TSOP-6	3000/Tape & Reel
SMS15CT1G	(Pb-Free)	oooo, tape a ricer
SMS24CT1G		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

$\textbf{SMS05C ELECTRICAL CHARACTERISTICS} \ (T_J = 25^{\circ}\text{C unless otherwise specified})$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse Working Voltage	V_{RWM}	(Note 2)			5.0	V
Breakdown Voltage	V_{BR}	I _T = 1.0 mA (Note 3)	6.2		7.2	V
Reverse Leakage Current	I _R	V _{RWM} = 5.0 V			5.0	μΑ
Clamping Voltage	V _C	I_{PP} = 5.0 A (8 \times 20 μ s Waveform)			9.8	V
Clamping Voltage	V _C	I _{PP} = 24 A (8 × 20 μs Waveform)			14.5	V
Maximum Peak Pulse Current	I _{PP}	8 × 20 μs Waveform			24	Α
Capacitance	CJ	V _R = 0 V, f = 1.0 MHz (Line to GND)		260	400	pF

SMS12C ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse Working Voltage	V_{RWM}	(Note 2)			12	V
Breakdown Voltage	V_{BR}	I _T = 1.0 mA (Note 3)	13.3		15	V
Reverse Leakage Current	I _R	V _{RWM} = 12 V		0.001	1.0	μΑ
Clamping Voltage	V _C	I_{PP} = 5.0 A (8 \times 20 μ s Waveform)			19	V
Clamping Voltage	V _C	I _{PP} = 15 A (8 × 20 μs Waveform)			23	V
Maximum Peak Pulse Current	I _{PP}	8 × 20 μs Waveform			15	Α
Capacitance	CJ	V _R = 0 V, f = 1.0 MHz (Line to GND)		120	150	pF

SMS15C ELECTRICAL CHARACTERISTICS ($T_J = 25$ °C, unless otherwise specified) (See Note 4)

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse Working Voltage	V _{RWM}	(Note 2)			15	V
Breakdown Voltage	V_{BR}	I _T = 1.0 mA (Note 3)	17		19	V
Reverse Leakage Current	I _R	V _{RWM} = 15 V		0.05	1.0	μΑ
Clamping Voltage	V _C	I_{PP} = 5.0 A (8 \times 20 μ s Waveform)			24	V
Clamping Voltage	V _C	I _{PP} = 12 A (8 × 20 μs Waveform)			29	V
Maximum Peak Pulse Current	I _{PP}	8 × 20 μs Waveform			12	Α
Capacitance	CJ	V _R = 0 V, f = 1.0 MHz (Line to GND)		95	125	pF

$\textbf{SMS24C ELECTRICAL CHARACTERISTICS} \ (T_J = 25^{\circ}C, \ unless \ otherwise \ specified)$

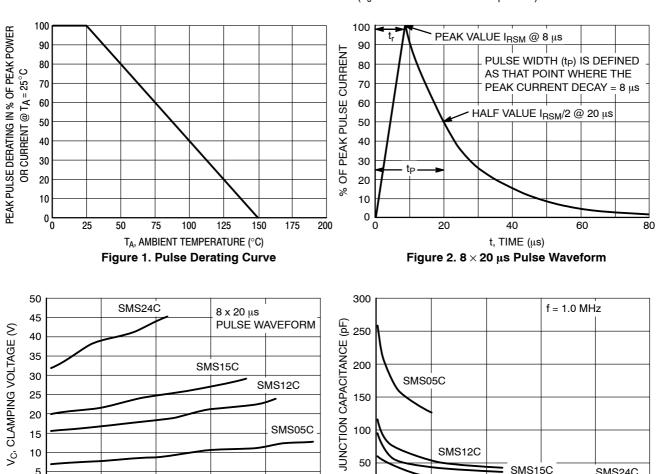
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse Working Voltage	V_{RWM}	(Note 2)			24	V
Breakdown Voltage	V_{BR}	I _T = 1.0 mA (Note 3)	26.7		32	V
Reverse Leakage Current	I _R	V _{RWM} = 24 V		0.001	1.0	μΑ
Clamping Voltage	V _C	I _{PP} = 5.0 A (8 × 20 μs Waveform)			40	V
Clamping Voltage	V _C	I _{PP} = 8 A (8 × 20 μs Waveform)			44	V
Maximum Peak Pulse Current	I _{PP}	8 × 20 μs Waveform			8.0	Α
Capacitance	CJ	V _R = 0 V, f = 1.0 MHz (Line to GND)		60	75	pF

^{2.} TVS devices are normally selected according to the working peak reverse voltage (V_{RWM}), which should be equal or greater than the DC or continuous peak operating voltage level.

3. V_{BR} is measured at pulse test current I_T.

4. Parametrics are the same for the Pb–Free packages, which are suffixed with a "G".

TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise specified)



I_{PP}, PEAK PULSE CURRENT (A) Figure 3. Clamping Voltage vs. Peak Pulse Current

15

20

25

0

10

10

5

0

0

5

Figure 4. Junction Capacitance vs. Reverse Voltage

V_{BR}, REVERSE VOLTAGE (V)

10

SMS15C

15

SMS24C

25

20

SMS12C

5

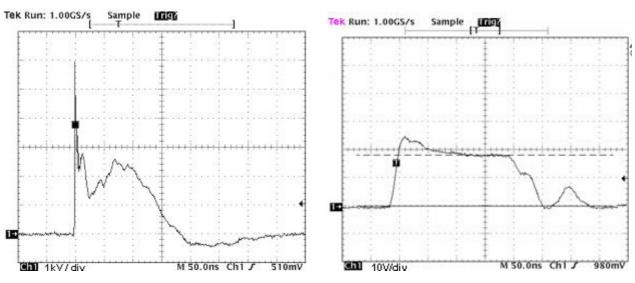


Figure 5. ESD Pulse IEC 61000-4-2 (8.0 kV Contact)

Figure 6. SMS15CT1 ESD Response for IEC 61000-4-2 (+8.0 kV Contact)

TYPICAL COMMON ANODE APPLICATIONS

A 5 TVS junction common anode design in a TSOP-6 package protects four separate lines using only one package. This adds flexibility and creativity to PCB design especially

when board space is at a premium. A simplified example of SMS05C Series Device applications is illustrated below.

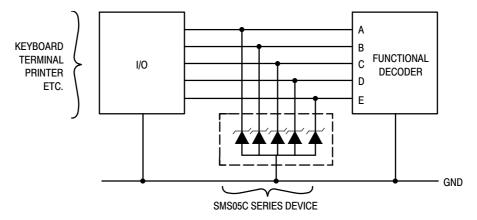


Figure 7. Computer Interface Protection

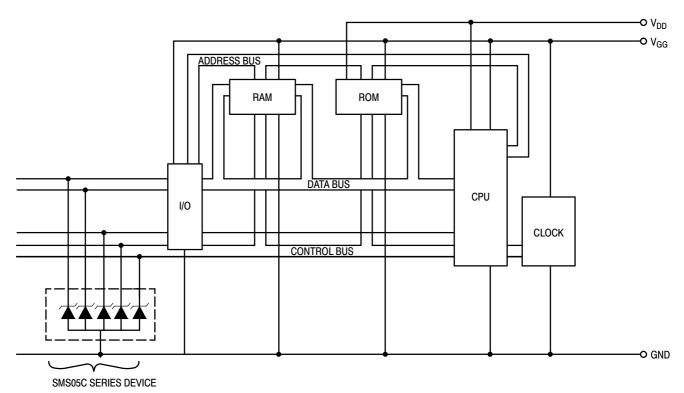
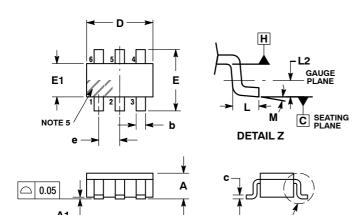


Figure 8. Microprocessor Protection

PACKAGE DIMENSIONS

TSOP-6 CASE 318G-02 **ISSUE U**



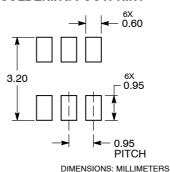
NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH.
- PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H
- 5. PIN ONE INDICATOR MUST BE LOCATED IN THE INDICATED ZONE.

	MILLIMETERS					
DIM	MIN	NOM	MAX			
Α	0.90	1.00	1.10			
A1	0.01	0.06	0.10			
b	0.25	0.38	0.50			
С	0.10	0.18	0.26			
D	2.90	3.00	3.10			
E	2.50	2.75	3.00			
E1	1.30	1.50	1.70			
е	0.85	0.95	1.05			
L	0.20	0.40	0.60			
L2	0.25 BSC					
М	0°	_	10°			

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice on semiconductor and are registered readerlands of semiconductor Components industries, Ite (SCILLC) and the series are injected to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA **Phone**: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative